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Product Specifications



Customer	Standard
Description	0.97" E-PAPER DISPLAY
Model Name	ET0097EP02-J
Date	2024/05/13
Revision	1.0

	Design Engineering		
	Approval	Check	Design



CONTENTS

1. Over View	3
2. Features	3
3. Mechanical and Optical Specification	4
4. Mechanical Drawing of EPD Module	5
5. Input/output Pin Assignment	6
6. Electrical Characteristics	7
7. Command Table.....	12
8. Block Diagram	45
9. Typical Application Circuit with SPI Interface.....	46
10 Typical Operating Sequence	47
11. Reliability Test.....	49
12. Quality Assurance	50
13. Mated Development Kit.....	54
14. Handling, Safety and Environment Requirements.....	55
15. Precautions.....	56

1. Over View

ET0097EP02-J is an Active Matrix EPD all-in-one driver with timing controller for ESL. The sources have 2-bit outputs per pixel to support white/black/red/yellow. The 0.97 inch active area contains 88x184 pixels. The module is a TFT-array driving electrophoresis display, with integrated circuits including gate driver, source driver, MCU interface, timing controller, oscillator, DC-DC, SRAM, LUT, VCOM. Module can be used in portable electronic devices, such as Electronic Shelf Label(ESL) System.

2. Features

- ◆88×184 pixels display
- ◆High contrast High reflectance
- ◆Ultra wide viewing angle Ultra low power consumption
- ◆Pure reflective mode
- ◆Bi-stable display
- ◆Commercial temperature range
- ◆Landscape portrait modes
- ◆Hard-coat antiglare display surface
- ◆Ultra Low current deep sleep mode
- ◆On chip display RAM
- ◆Waveform can be stored in On-chip OTP or written by MCU
- ◆Serial peripheral interface available
- ◆On-chip oscillator
- ◆On-chip booster and regulator control for generating VCOM, Gate and Source driving voltage
- ◆I²C signal master interface to read external temperature sensor
- ◆Built-in temperature sensor

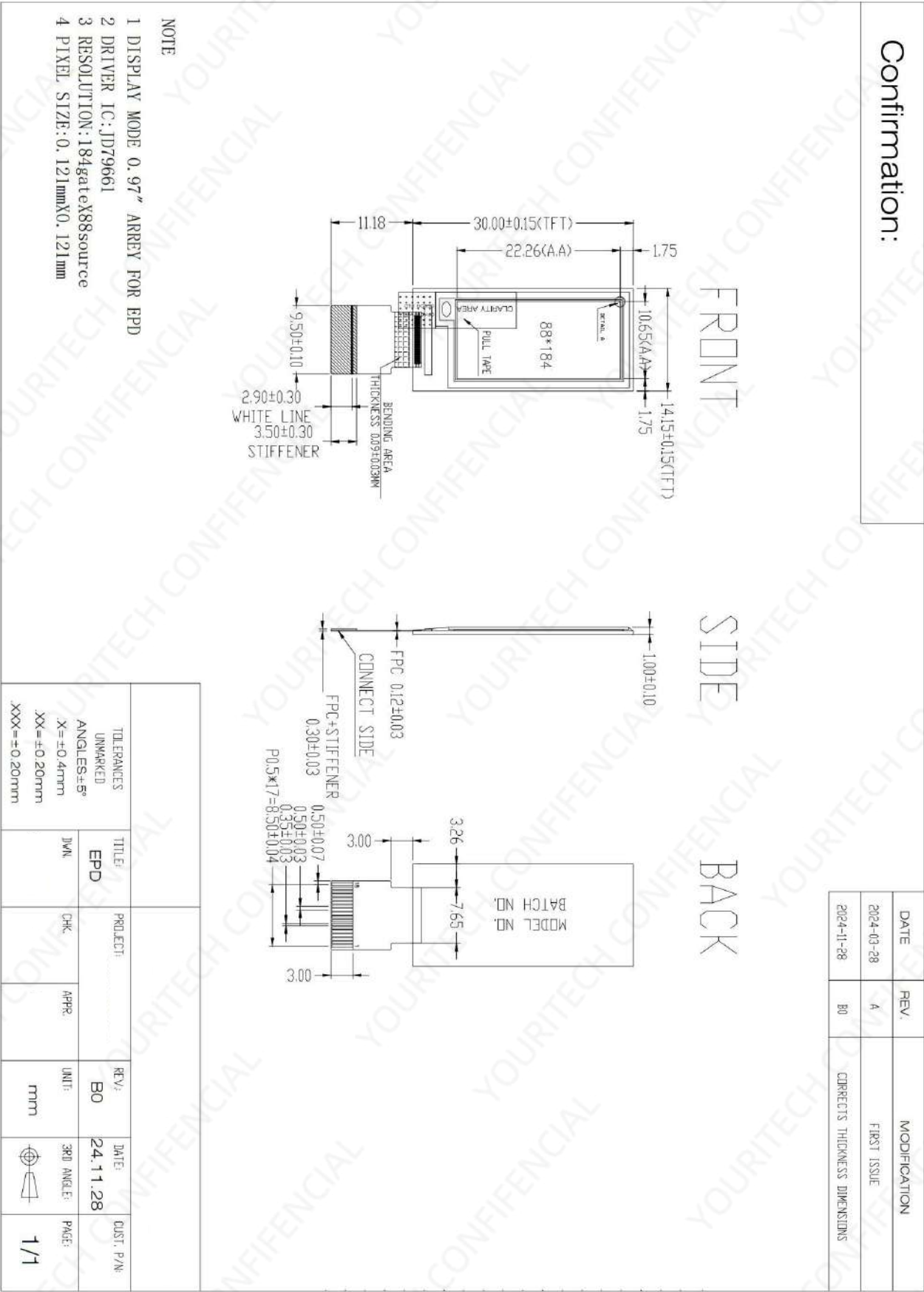
3. Mechanical and Optical Specification

Parameter	Specifications	Unit	Remark
Screen Size	0.97	Inch	
Display Resolution	88(H)×184(V)	Pixel	DPI:210
Active Area	10.65×22.26	mm	
Pixel Pitch	0.121×0.121	mm	
Pixel Configuration	Square		
Outline Dimension	14.15(H)×30 (V) × 1.0(D)	mm	
Weight	1.1±0.5	g	

Temperature Range(°C)		0-9	10-19	20-29	30-40	Units
White State	TYP L*	64	63	63	63	
	MIN L*	62	62	62	62	
	a*	≤0	≤0	≤0	≤0	
	b*	≤2.5	≤2.5	≤2.5	≤2.5	
Black State	TYP L*	9	9	9	9	
	MAX L*	11	11	11	11	
	a*	≤9	≤9	≤8	≤10	
Red State	MIN L*	23	23	24	23	
	TYP a*	36	38	40	40	
	MIN a*	34	34	38	38	
	MAX b*	34	34	34	34	
Yellow State	MIN L*	50	50	54	54	
	TYP b*	55	63	66	66	
	MIN b*	53	56	60	60	
	MAX a*	18	18	18	18	
Ghosting		≤2	≤2	≤2	≤2	delta E

Notes: 3-1. Luminance meter: Eye-One Pro Spectrophotometer.

4. Mechanical Drawing of EPD Module



5. Input/output Pin Assignment

No.	Name	I/O	Description	Remark
1	GDR	O	N-Channel MOSFET Gate Drive Control	
2	RESE	I	Current Sense Input for the Control Loop	
3	VSH2	C	Positive Source driving voltage2	
4	BUSY	O	Busy state output pin	Note 5-4
5	RES#	I	Reset signal input. Active Low.	Note 5-3
6	D/C#	I	Data /Command control pin	Note 5-2
7	CS#	I	Chip select input pin	Note 5-1
8	SCL	I	Serial Clock pin (SPI)	
9	SDA	I/O	Serial Data pin (SPI)	
10	VCI	P	Power Supply for the chip	
11	VSS	P	Ground	
12	VDD	C	Core logic power pin VDD can be regulated internally from VCI. A capacitor should be connected between VDD and VSS	
13	VPP	P	FOR TEST	Keep Open
14	VSH1	C	Positive Source driving voltage	
15	VGH	C	Power Supply pin for Positive Gate driving voltage and VSH1	
16	VSL	C	Negative Source driving voltage	
17	VGL	C	Power Supply pin for Negative Gate driving voltage VCOM and VSL	
18	VCOM	C	VCOM driving voltage	

I = Input Pin, O =Output Pin, I/O = Bi-directional Pin (Input/output), P = Power Pin, C = Capacitor Pin

Note 5-1: This pin (CS#) is the chip select input connecting to the MCU. The chip is enabled for MCU communication only when CS# is pulled LOW.

Note 5-2: This pin is (D/C#) Data/Command control pin connecting to the MCU in 4-wire SPI mode. When the pin is pulled HIGH, the data at SDA will be interpreted as data. When the pin is pulled LOW, the data at SDA will be interpreted as command.

Note 5-3: This pin (RES#) is reset signal input. The Reset is active low.

Note 5-4: This pin is Busy state output pin. When Busy is Low, the operation of chip should not be interrupted, command should not be sent. The chip would put Busy pin Low when -Outputting display waveform -Communicating with digital temperature sensor

Note 5-5: Bus interface selection pin

Note 5-6: This pin connect to the VSS if there is no external temperature sensor.

BS1 State	MCU Interface
L	4-lines serial peripheral interface(SPI) - 8 bits SPI
H	3- lines serial peripheral interface(SPI) - 9 bits SPI

6. Electrical Characteristics

6.1 Absolute Maximum Rating

Parameter	Symbol	Rating	Unit
Logic supply voltage	VCI	-0.3 to +6.0	V
Logic Input voltage	VIN	-0.3 to VCI +0.3	V
Operating Temp range	TOPR	0 to +40	°C.
Storage Temp range	TSTG	-25 to +70	°C.
Optimal Storage Humidity	HST Go	55±10	%RH

Note:

1. Maximum ratings are those values beyond which damages to the device may occur. Functional operation should be restricted to the limits in the Panel DC Characteristics tables.

2. The storage time is within 10 days for -25°C ~ 70°C.

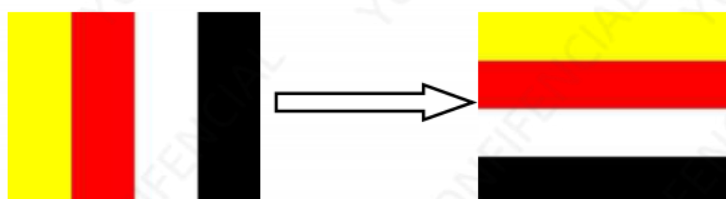
The display screen should be kept white and face up.

6.2 Panel DC Characteristics

The following specifications apply for: VSS=0V, VCI=3.0V, TOPR =23°C.

Parameter	Symbol	Condition	Applicable pin	Min.	Typ.	Max.	Unit
Single ground	VSS	-		-	0	-	V
Logic supply voltage	VCI	-	VCI	2.3	3.0	3.6	V
Core logic voltage	VDD		VDD	2.3	3.0	3.6	V
High level input voltage	VIH	-	-	0.7 VCI	-	VCI	V
Low level input voltage	VIL	-	-	0	-	0.3 VCI	V
High level output voltage	VOH	IOH = 400Ma	-	VCI -0.4	-	-	V
Low level output voltage	VOL	IOL = -400Ma	-	-	-	GND +0.4	V
Typical power	PTYP	VCI=3.0V	-	-	9	-	mW
Deep sleep mode	PSTPY	VCI=3.0V	-	-	0.0012	-	mW
Typical operating current	Iopr_VCI	VCI=3.0V	-	-	3	-	mA
Full/Fast image update	-	23 °C	-	-	20/12	-	sec
Deep sleep mode current	Idslp_VCI	DC/DC off No clock No input load Ram data not retain	-	-	0.4	1	uA

Notes: 1. The typical power is measured with following transition from horizontal 4 scale pattern to vertical 4 scale pattern.



2. The deep sleep power is the consumed power when the panel controller is in deep sleep mode.
3. The listed electrical/optical characteristics are only guaranteed under the controller & waveform provided by YOURITECH.
4. Electrical measurement: Tektronix oscilloscope - MDO3024,
Tektronix current probe-TCP0030A.



6.3 Panel AC Characteristics

6.3.1 MCU Interface Selection

The pin assignment at different interface mode is summarized in Table 6-3-1. Different MCU mode can be set by hardware selection on BS1 pins. The display panel only supports 4-wire SPI or 3-wire SPI interface mode.

Pin Name	Data/Command Interface		Control Signal		
Bus interface	SDA	SCL	CS#	D/C#	RES#
BS1=L 4-wire SPI	SDA	SCL	CS#	D/C#	RES#
BS1=H 3-wire SPI	SDA	SCL	CS#	L	RES#

Table 6-3-1: MCU interface assignment under different bus interface mode

6.3.2 MCU Serial Interface (4-wire SPI)

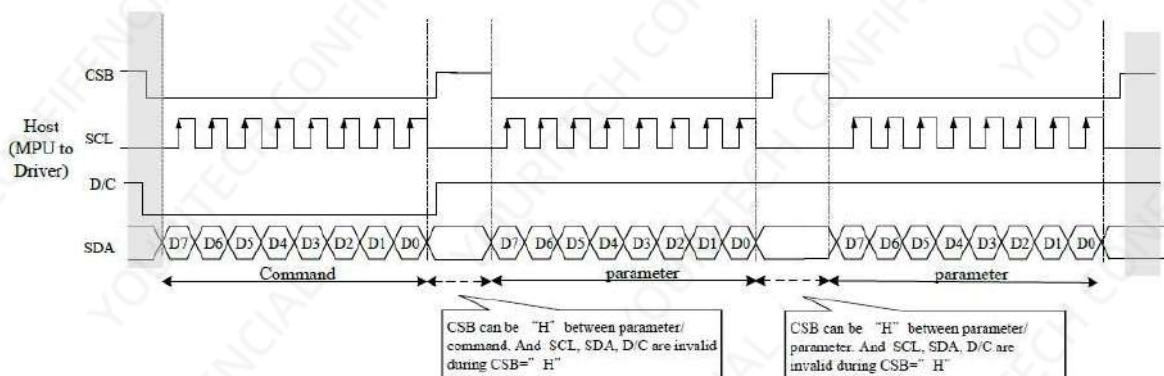
The serial interface consists of serial clock SCL, serial data SDA, D/C#, CS#. This interface supports Write mode and Read mode.

Function	CS#	D/C#	SCL
Write command	L	L	↑
Write data	L	H	↑

Table 6-3-2: Control pins of 4-wire Serial Peripheral interface

Note: ↑ stands for rising edge of signal

Figure 6-3-1: 4-wire SPI mode



Serial Interface Timing Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
SERIAL COMMUNICATION						
CSB	T_{CSS}	60			ns	Chip select setup time
	T_{CSH}	65			ns	Chip select hold time
	T_{SCC}	20			ns	Chip select CSB setup time
	T_{CHW}	40			ns	Chip select setup time
SCL	T_{SCYCW}	100			ns	Serial clock cycle (Write)
	T_{SHW}	35			ns	SCL "H" pulse width (Write)
	T_{SLW}	35			ns	SCL "L" pulse width (Write)
	T_{SCYCR}	150			ns	Serial clock cycle (Read)
	T_{SHR}	60			ns	SCL "H" pulse width (Read)
	T_{SLR}	60			ns	SCL "L" pulse width (Read)
SDA (DIN) (DOUT)	T_{SDS}	30			ns	Data setup time
	T_{SDH}	30			ns	Data hold time
	T_{ACC}			10	ns	Access time
	T_{OH}	15			ns	Output disable time
D/C	T_{DCS}	20			ns	DC setup time
	T_{DCH}	20			ns	DC hold time

7.Command Table

R/W: 0:Write Cycle 1:Read Cycle D/CX:0:Command/1:Data D7~D0:-:Don't Care

1)R00H (PSR): Panel setting Register

R00H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
PSR	W	0	0	0	0	0	0	0	0	0	00H
1 st Parameter	W	1	RES[1]	RES[0]	PST_MODE	-	UD	SHL	SHD_N	RST_N	0Fh
2 nd Parameter	W	1	LUT_EN	-	FOPT	VCMZ	TS_AUTO	TIEG	NORG	VC_LUTZ	09h

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command defines as :		
	1 st parameter		
	Bit	Name	Description
	0	RST_N	RST_N function 1: no effect. (default) 0: Booster OFF, Register data are set to their default values, and Source/Boder/Vcom: floating
	1	SHD_N	SHD_N function 0 : Booster OFF, register data are kept, and Source/Boder/Vcom are kept 0V or floating. 1 : Booster on. (default)
	2	SHL	SHL function 0: Shift left; First data=Sn→Sn-1 →...→S2→Last data=S1. 1: Shift right; First data=S1→S2 →...→Sn-1→Last data=Sn. (default)
	3	UD	UD function 0: Scan down; First line=Gn→Gn-1 →...→G2→Last line=G1. 1: Scan up; First line=G1→G2 →...→Gn-1→Last line=Gn. (default)
	5	PST_MODE	Power switch operation mode 0: Power switching time in the period of frame scanning. (default) 1: Power switching time in the external period before frame scanning.
	7-6	RES[1,0]	Resolution setting 00: Display resolution is 176x296 (default) 01: Display resolution is 128x296 10: Display resolution is 128x250 11: Display resolution is 112x204

2 nd parameter		
Bit	Name	Description
0	VC_LUTZ	VCOM status function 0 : No effect 1 : After refreshing display,the output of VCOM is set to floating automatically (default)
1	NORG	VCOM status function 0 : No effect (default) 1 : After refreshing display, VCOM is tied to GND before power off
2	TIEG	VGN power off status function 0 : No effect (default) 1 : Power off, VGN will be tied to GND
3	TS_AUTO	Temperature sensing will be activated automatically one time 0 : Before enabling booster, Temperature Sensor will be activated automatically one time. 1 : When RST_N low to high, Temperature Sensor will be activated automatically one time. (default)
4	VCMZ	VCOM status function 0 : No effect (default) 1 : VCOM is always floating
5	FOPT	FOPT function 0: Scan 1 frame after waveform finished(default) 1: No scan after waveform finished and switch the source channel output to Hiz.
7	LUT_EN	LUT selection setting 0 : Using LUT from MTP(default) 1 : Using LUT from register
Priority of VCOM setting: VCMZ > NORG > FOPT > VC_LUTZ FOPT setting is part of refreshing display. FOPT: Power off floating. Notes: 1. Non-select gate line keep at VGN for DSP/DRF and AMV 2. Dummy source line follow LUTC for DSP/DRF 3. When SHD_N become low, DCDC will turn off. Register and SRAM data will keep until VDD turn off. SD output and VCOM will base on previous condition. It may have two condition: 0V or floating. 4. When RST_N become low, driver will reset. All register will reset to default value. All of the driver's functions will disable. Source/Gate/Border/VCOM will be released to floating		
Restriction		

2) R01H (PWR): Power setting Register

R01H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
PWR	W	0	0	0	0	0	0	0	0	1	01h
1 st Parameter	W	1	-	-	-	-	V_MODE	VSC_EN	VDS_EN	VDG_EN	07h
2 nd Parameter	W	1	-	-	-	-	-	-	VGPN [1]	VGPN [0]	00h
3 rd Parameter	W	1	-	VSPL_0 [6:0]							00h
4 th Parameter	W	1	-	VSP_1 [6:0]							00h
5 th Parameter	W	1	-	VSN_1 [6:0]							00h
6 th Parameter	W	1	-	VSPL_1 [6:0]							00h

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command defines as :	
	1 st Parameter:	
	Bit	Name
	0	VDG_EN
	1	VDS_EN
	2	VSC_EN
	3	V_MODE
	2nd Parameter:	
	Bit	Name
	1-0	VGPN

3rd & 4th & 6th Parameter: Internal VSP_1/VSP_0/ VSPL_1 power selection

Bit	Name	Description								
6-0	VSP_1 & VSPL_0 & VSPL_1	Internal VSP & VSPL power selection.								
		bit[6:0]		Voltage(V)	bit[6:0]		Voltage(V)	bit[6:0]		Voltage(V)
		0000000	00h	3	0101001	29h	7.1	1010010	52h	11.2
		0000001	01h	3.1	0101010	2Ah	7.2	1010011	53h	11.3
		0000010	02h	3.2	0101011	2Bh	7.3	1010100	54h	11.4
		0000011	03h	3.3	0101100	2Ch	7.4	1010101	55h	11.5
		0000100	04h	3.4	0101101	2Dh	7.5	1010110	56h	11.6
		0000101	05h	3.5	0101110	2Eh	7.6	1010111	57h	11.7
		0000110	06h	3.6	0101111	2Fh	7.7	1011000	58h	11.8
		0000111	07h	3.7	0110000	30h	7.8	1011001	59h	11.9
		0001000	08h	3.8	0110001	31h	7.9	1011010	5Ah	12
		0001001	09h	3.9	0110010	32h	8	1011011	5Bh	12.1
		0001010	0Ah	4	0110011	33h	8.1	1011100	5Ch	12.2
		0001011	0Bh	4.1	0110100	34h	8.2	1011101	5Dh	12.3
		0001100	0Ch	4.2	0110101	35h	8.3	1011110	5Eh	12.4
		0001101	0Dh	4.3	0110110	36h	8.4	1011111	5Fh	12.5
		0001110	0Eh	4.4	0110111	37h	8.5	1100000	60h	12.6
		0001111	0Fh	4.5	0111000	38h	8.6	1100001	61h	12.7
		0010000	10h	4.6	0111001	39h	8.7	1100010	62h	12.8
		0010001	11h	4.7	0111010	3Ah	8.8	1100011	63h	12.9
		0010010	12h	4.8	0111011	3Bh	8.9	1100100	64h	13
		0010011	13h	4.9	0111100	3Ch	9	1100101	65h	13.1
		0010100	14h	5	0111101	3Dh	9.1	1100110	66h	13.2
		0010101	15h	5.1	0111110	3Eh	9.2	1100111	67h	13.3
		0010110	16h	5.2	0111111	3Fh	9.3	1101000	68h	13.4
		0010111	17h	5.3	1000000	40h	9.4	1101001	69h	13.5
		0011000	18h	5.4	1000001	41h	9.5	1101010	6Ah	13.6
		0011001	19h	5.5	1000010	42h	9.6	1101011	6Bh	13.7
		0011010	1Ah	5.6	1000011	43h	9.7	1101100	6Ch	13.8
		0011011	1Bh	5.7	1000100	44h	9.8	1101101	6Dh	13.9
		0011100	1Ch	5.8	1000101	45h	9.9	1101110	6Eh	14
		0011101	1Dh	5.9	1000110	46h	10	1101111	6Fh	14.1
		0011110	1Eh	6	1000111	47h	10.1	1110000	70h	14.2
		0011111	1Fh	6.1	1001000	48h	10.2	1110001	71h	14.3
		0100000	20h	6.2	1001001	49h	10.3	1110010	72h	14.4
		0100001	21h	6.3	1001010	4Ah	10.4	1110011	73h	14.5
		0100010	22h	6.4	1001011	4Bh	10.5	1110100	74h	14.6
		0100011	23h	6.5	1001100	4Ch	10.6	1110101	75h	14.7
		0100100	24h	6.6	1001101	4Dh	10.7	1110110	76h	14.8
		0100101	25h	6.7	1001110	4Eh	10.8	1110111	77h	14.9
		0100110	26h	6.8	1001111	4Fh	10.9	1111000	78h	15
		0100111	27h	6.9	1010000	50h	11	other	15	
		0101000	28h	7	1010001	51h	11.1			

5th Parameter: Internal VSN_1 power selection

Bit	Name	Description					
6-0	VSN_1	Internal VSN power selection:					
		bit(6:0)	Voltage(V)	bit(6:0)	Voltage(V)	bit(6:0)	Voltage(V)
		0000000	00h	-3	0101001	29h	-7.1
		0000001	01h	-3.1	0101010	2Ah	-7.2
		0000010	02h	-3.2	0101011	2Bh	-7.3
		0000011	03h	-3.3	0101100	2Ch	-7.4
		0000100	04h	-3.4	0101101	2Dh	-7.5
		0000101	05h	-3.5	0101110	2Eh	-7.6
		0000110	06h	-3.6	0101111	2Fh	-7.7
		0000111	07h	-3.7	0110000	30h	-7.8
		0001000	08h	-3.8	0110001	31h	-7.9
		0001001	09h	-3.9	0110010	32h	-8
		0001010	0Ah	-4	0110011	33h	-8.1
		0001011	0Bh	-4.1	0110100	34h	-8.2
		0001100	0Ch	-4.2	0110101	35h	-8.3
		0001101	0Dh	-4.3	0110110	36h	-8.4
		0001110	0Eh	-4.4	0110111	37h	-8.5
		0001111	0Fh	-4.5	0111000	38h	-8.6
		0010000	10h	-4.6	0111001	39h	-8.7
		0010001	11h	-4.7	0111010	3Ah	-8.8
		0010010	12h	-4.8	0111011	3Bh	-8.9
		0010011	13h	-4.9	0111100	3Ch	-9
		0010100	14h	-5	0111101	3Dh	-9.1
		0010101	15h	-5.1	0111110	3Eh	-9.2
		0010110	16h	-5.2	0111111	3Fh	-9.3
		0010111	17h	-5.3	1000000	40h	-9.4
		0011000	18h	-5.4	1000001	41h	-9.5
		0011001	19h	-5.5	1000010	42h	-9.6
		0011010	1Ah	-5.6	1000011	43h	-9.7
		0011011	1Bh	-5.7	1000100	44h	-9.8
		0011100	1Ch	-5.8	1000101	45h	-9.9
		0011101	1Dh	-5.9	1000110	46h	-10
		0011110	1Eh	-6	1000111	47h	-10.1
		0011111	1Fh	-6.1	1001000	48h	-10.2
		0100000	20h	-6.2	1001001	49h	-10.3
		0100001	21h	-6.3	1001010	4Ah	-10.4
		0100010	22h	-6.4	1001011	4Bh	-10.5
		0100011	23h	-6.5	1001100	4Ch	-10.6
		0100100	24h	-6.6	1001101	4Dh	-10.7
		0100101	25h	-6.7	1001110	4Eh	-10.8
		0100110	26h	-6.8	1001111	4Fh	-10.9
		0100111	27h	-6.9	1010000	50h	-11
		0101000	28h	-7	1010001	51h	-7.1
		other					-15

Notes:

1. VSP_0/VSN_0 voltage output is ± 15 V fixed value.
2. When switching Mode0 or Mode1, the voltage output is:
 Mode0: VSP_0(+15) / VSN_0 (-15) / VSPL_0 (+3--+15)
 Mode1: VSP_1(+3 - +15) / VSN_1(-3 - -15) / VSPL_1(+3 - +15)

	Mode0	Mode1
VSP	VSP_0(+15)	VSP_1(+3--+15)
VSN	VSN_0(-15)	VSN_1(-3--15)
VSPL	VSPL_0(+3--+15)	VSPL_1(+3 - +15)

3. If gate voltage is set to ± 15 v, ± 10 v, IC will auto correct source voltage as follows

I. VGP- VSP_0 / VSPL_0 / VSP_1 / VSPL_1 ≥ 2 v

II. VGN- VSN_0 / VSN_1 ≥ -2 v

For example:

	symbol	Voltage setting	Real Voltage
Voltage	VGP	10v	+10v
	VGN	10v	-10v
	VSP_0	+15v	+8v
	VSN_0	-15v	-8v
	VSP_1	+5v	+5v
	VSN_1	-5v	-5v
	VSPL	+15v	+8v
	VCOMH	+15v+(-2v)	+8v+(-2v)
	VCOML	-15v+(-2v)	-8v+(-2v)
	VCOMDC	-2v	-2v

4. Voltage setting limit: VSP_0 $\geq$ VSPL_0 , VSP_1 $\geq$ VSPL_1

Restriction

3)R02H (POF): Power OFF Command

[illegible]

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command defines as : ● After power off command, driver will power off base on power off sequence. ● After power off command, BUSY_N signal will drop from high to low. When finish the power off sequence, BUSY_N signal will rise from low to high. ● Power off command will turn off charge pump, T-con, source driver, gate driver, VCOM, temperature sensor, but register and SRAM data will keep until VDD off. ● SD output and VCOM will base on previous condition. It may have two conditions: 0v or floating. 1st parameter <table> <tr> <th>Bit</th><th>Name</th><th>Description</th></tr> <tr> <td>0</td><td>EDSE</td><td>EPD Discharge Trigger 0 : Disable EPD discharge (default) 1 : Enable EPD discharge</td></tr> </table>	Bit	Name	Description	0	EDSE	EPD Discharge Trigger 0 : Disable EPD discharge (default) 1 : Enable EPD discharge
Bit	Name	Description					
0	EDSE	EPD Discharge Trigger 0 : Disable EPD discharge (default) 1 : Enable EPD discharge					
Restriction	This command only active when BUSY_N = "1".						

4)R03H (PFS): Power off Sequence Setting Register

R03H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
PFS	W	0	0	0	0	0	0	0	1	1	03H
1 st Parameter	W	1	-		T_VDPG_OFF [1:0]		-		T_VDS_OFF [1:0]		00h
2 nd Parameter	W	1	VGP_LEN[3:0]				VGP_EXT[3:0]				54h
3 rd Parameter	W	1	XON_DLY[3:0]				XON_LEN[3:0]				44h

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command defines as :		
1 st Parameter:			
Bit	Name	Description	
1-0	T_VDS_OFF	Power off sequence of VSP /VSN 00: 20 ms (default) 01: 40 ms 10: 60 ms 11: 80 ms	
5-4	T_VDPG_OFF	Power off sequence of VGP and VGN 00: 20 ms (default) 01: 40 ms 10: 60 ms 11: 80 ms	
2 nd Parameter			
Bit	Name	Description	
1-0	VGP_EXT	VGP extension time 0000: 0 ms 0001: 500 ms 0010: 1000 ms 0011: 1500 ms 0100: 2000 ms (default) 0101: 2500 ms 0110: 3000 ms 0111: 3500 ms 1000: 4000 ms 1001: 4500 ms 1010: 5000 ms 1011: 5500 ms 1100: 6000 ms 1101: 6500 ms	
7-4	VGP_LEN	When power off, the length of time VGP stay 10V 0000: 0 ms 0001: 500 ms 0010: 1000 ms 0011: 1500 ms 0100: 2000 ms 0101: 2500 ms (default) 0110: 3000 ms 0111: 3500 ms 1000: 4000 ms 1001: 4500 ms 1010: 5000 ms 1011: 5500 ms	

			1100: 6000 ms 1101: 6500 ms
3*Parameter:			
Bit	Name	Description	
3-0	XON_LEN	XON enable time 0000: 0 ms 0001: 500 ms 0010: 1000 ms 0011: 1500 ms 0100: 2000 ms (default) 0101: 2500 ms 0110: 3000 ms 0111: 3500 ms 1000: 4000 ms 1001: 4500 ms 1010: 5000 ms 1011: 5500 ms 1100: 6000 ms	
7-4	XON_DLY	XON delay time 0000: 0 ms 0001: 500 ms 0010: 1000 ms 0011: 1500 ms 0100: 2000 ms (default) 0101: 2500 ms 0110: 3000 ms 0111: 3500 ms 1000: 4000 ms 1001: 4500 ms 1010: 5000 ms 1011: 5500 ms 1100: 6000 ms	
Restriction			

5)(R04H) (PON):Power ON Command

R04H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
PON	W	0	0	0	0	0	0	1	0	0	04H

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command defines as : - After power on command, driver will power on base on power on sequence. - After power on command, BUSY_N signal will drop from high to low. When finishing the power on sequence(base on PWR command), BUSY_N signal will rise from low to high.
Restriction	This command only active when BUSY_N = "1".

Description		Bit[5:0]	Description	Bit[5:0]	Description	Bit[5:0]	Description
Minimum OFF time setting of PHA_OFF & PHB_OFF & PHC_OFF		000000	Period1	010110	Period23	101100	Period45
		000001	Period2	010111	Period24	101101	Period46
		000010	Period3	011000	Period25	101110	Period47
		000011	Period4	011001	Period26	101111	Period48
		000100	Period5	011010	Period27	110000	Period49
		000101	Period6	011011	Period28	110001	Period50
		000110	Period7	011100	Period29	110010	Period51
		000111	Period8	011101	Period30	110011	Period52
		001000	Period9	011110	Period31	110100	Period53
		001001	Period10	011111	Period32	110101	Period54
		001010	Period11	100000	Period33	110110	Period55
		001011	Period12	100001	Period34	110111	Period56
		001100	Period13	100010	Period35	111000	Period57
		001101	Period14	100011	Period36	111001	Period58
		001110	Period15	100100	Period37	111010	Period59
		001111	Period16	100101	Period38	111011	Period60
		010000	Period17	100110	Period39	111100	Period61
		010001	Period18	100111	Period40	111101	Period62
		010010	Period19	101000	Period41	111110	Period63
		010011	Period20	101001	Period42	111111	Period64
		010100	Period21	101010	Period43		
		010101	Period22	101011	Period44		
Restriction							

7) R07H (DSLP): Deep Sleep Command

R07H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
DSLP	W	0	0	0	0	0	0	1	1	1	07H
1 st Parameter	W	1	1	0	1	0	0	1	0	1	A5h

NOTE: "-" Don't care, can be set to VDD or GND level

Description	The command define as follows: After this command is transmitted, the chip would enter the deep-sleep mode to save power. The deep sleep mode would return to standby by hardware reset. The only one parameter is a check code, the command would be excited if check code = 0xA5.
Restriction	This command only active when BUSY_N = "1".

8) R10H (DTM): Data Start transmission Register

R10H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
DTM	W	0	0	0	0	1	0	0	0	0	10H
2 bit mode	W	1									
1 st Parameter	W	1	Pixel1		Pixel2		Pixel3		Pixel4		00h
⋮	W	1	⋮		⋮		⋮		⋮		00h
M th Parameter	W	1	Pixel(n-3)		Pixel(n-2)		Pixel(n-1)		Pixel(n)		00h

NOTE: "-" Don't care, can be set to VDD or GND level

Description

The command define as follows:

The register is indicates that user start to transmit data, then write to SRAM. While data transmission complete, user must send command 12H. Then chip will start to send data/VCOM for panel.

Pixel [1~n][1:0]: 2-bit/pixel

Image Data	DDX=1 (default)		DDX=0	
Pixel[1:0]	Gray level select	IP output LUT select	Gray level select	IP output LUT select
00b	Gray0	ogray00	Gray3	ogray03
01b	Gray1	ogray01	Gray2	ogray02
10b	Gray2	ogray02	Gray1	ogray01
11b	Gray3	ogray03	Gray0	ogray00

Data mapping example:

When DDX=1, Pixel[1:0]=01 -> Gray level select=Gray1, follow LUT data output from IP output port"ogray01".

When DDX=0, Pixel[1:0]=11 -> Gray level select=Gray0, follow LUT data output from IP output port"ogray00"

Restriction

9)R11H (DSP): Data Stop Command

R11H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
DSP	W	0	0	0	0	1	0	0	0	1	11H
1 st Parameter	R	1	Data_flag	-	-	-	-	-	-	-	-

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command defines as : While finished the data transmitting, user must send this command to driver and read Data_flag information. 1st Parameter: <table><tr><th>Bit</th><th>Name</th><th>Description</th></tr><tr><td>7</td><td>Data_flag</td><td>0: Driver didn't receive all the data. 1: Driver has already received all of the one frame data.</td></tr></table> After "Data Start" (10h) or "Data Stop" (11h) commands and when data_flag=1, BUSY_N signal will become "0" and the refreshing of panel starts.	Bit	Name	Description	7	Data_flag	0: Driver didn't receive all the data. 1: Driver has already received all of the one frame data.
Bit	Name	Description					
7	Data_flag	0: Driver didn't receive all the data. 1: Driver has already received all of the one frame data.					
Restriction	This command only actives when BUSY_N = "1".						

10)R12H (DRF): Display Refresh Command

R12H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
DRF	W	0	0	0	0	1	0	0	1	0	12H
1 st Parameter	W	1	-	-	-	-	-	-	-	AC/DC VCOM	00h

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command defines as : While users send this command, driver will refresh display (data/VCOM) base on SRAM data and LUT. AC/DC VCOM: 0: AC VCOM, VCOM will follow LUTC when updating image. (default) 1: DC VCOM, VCOM will always be VCOMDC when updating image After display refresh command, BUSY_N signal will become "0"
Restriction	This command only actives when BUSY N = "1"

11) R17H (AUTO): Auto Sequence

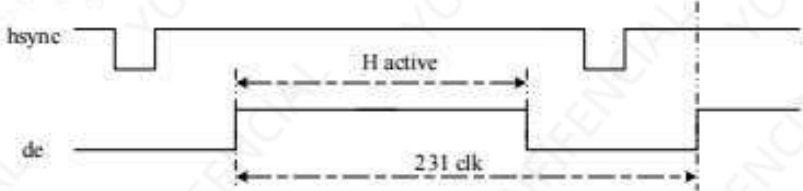
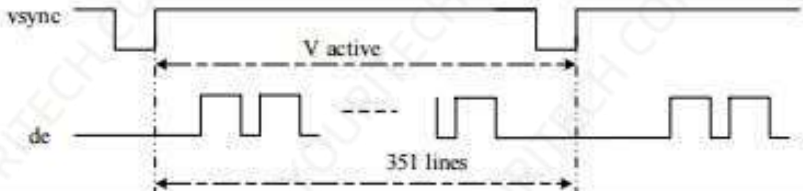
R17H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
Auto Sequence	W	0	0	0	0	1	0	1	1	1	17H
1 st Parameter	W	1	Code[7]	Code[6]	Code[5]	Code[4]	Code[3]	Code[2]	Code[1]	Code[0]	A5h

Description	The command can enable the internal sequence to execute several commands continuously. The successive execution can minimize idle time to avoid unnecessary power consumption and reduce the complexity of host's control procedure. The sequence contains several operations, including PON, DRF, POF, DSLP. AUTO (0x17) + Code(0xA5) = (PON→DRF→POF) AUTO (0x17) + Code(0xA7) = (PON→DRF→POF→DSLP)
Restriction	This command only actives when BUSY_N = "1".

12) R30H (PLL): PLL Control Register

R30H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
PLL	W	0	0	0	1	1	0	0	0	0	30H
1 st Parameter	W	1	-	-	-	-	Dyna	FR[2]	FR[1]	FR[0]	02h

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command defines as: The command controls the PLL clock frequency. The PLL structure must support the following frame rates: <table border="1"> <thead> <tr> <th>bit3</th><th>Dynamic frame rate</th></tr> </thead> <tbody> <tr> <td>0</td><td>Disable (default)</td></tr> <tr> <td>1</td><td>Enable</td></tr> </tbody> </table> <table border="1"> <thead> <tr> <th>FR[2:0]</th><th>Frame rate</th></tr> </thead> <tbody> <tr> <td>000</td><td>12.5 Hz</td></tr> <tr> <td>001</td><td>25 Hz</td></tr> <tr> <td>010</td><td>50 Hz (default)</td></tr> <tr> <td>011</td><td>65 Hz</td></tr> <tr> <td>100</td><td>75 Hz</td></tr> <tr> <td>101</td><td>85 Hz</td></tr> <tr> <td>110</td><td>100 Hz</td></tr> <tr> <td>111</td><td>120 Hz</td></tr> </tbody> </table>	bit3	Dynamic frame rate	0	Disable (default)	1	Enable	FR[2:0]	Frame rate	000	12.5 Hz	001	25 Hz	010	50 Hz (default)	011	65 Hz	100	75 Hz	101	85 Hz	110	100 Hz	111	120 Hz
bit3	Dynamic frame rate																								
0	Disable (default)																								
1	Enable																								
FR[2:0]	Frame rate																								
000	12.5 Hz																								
001	25 Hz																								
010	50 Hz (default)																								
011	65 Hz																								
100	75 Hz																								
101	85 Hz																								
110	100 Hz																								
111	120 Hz																								
remark	-Horizontal  -Vertical 																								
Restriction																									

13)R40H (TSC): Temperature Sensor Command

R40H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
TSC	W	0	0	1	0	0	0	0	0	0	40H
1 st Parameter	R	1	D10/TS[7]	D9/TS[6]	D8/TS[5]	D7/TS[4]	D6/TS[3]	D5/TS[2]	D4/TS[1]	D3/TS[0]	-
2 nd Parameter	R	1	D2/TS[9]	D1/TS[8]	D0	-	-	-	-	-	-

NOTE: "-" Don't care, can be set to VDD or GND level

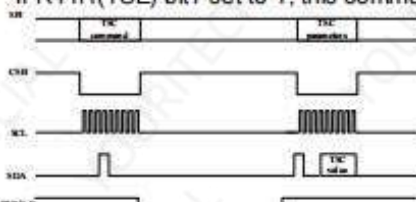
Description

-The command define as follows:

This command indicates the temperature value.

If R41H(TSE) bit7 set to 0, this command reads internal temperature sensor value.

If R41H(TSE) bit7 set to 1, this command reads external (LM75) temperature sensor value



TS[7:0]D[10:3]	T (°C)	TS[7:0]D[10:3]	T (°C)	TS[7:0]D[10:3]	T (°C)
11100111	-25	00000000	0	00011001	25
11101000	-24	00000001	1	00011010	26
11101001	-23	00000010	2	00011011	27
11101010	-22	00000011	3	00011100	28
11101011	-21	00000100	4	00011101	29
11101100	-20	00000101	5	00011110	30
11101101	-19	00000110	6	00011111	31
11101110	-18	00000111	7	00100000	32
11101111	-17	00001000	8	00100001	33
11110000	-16	00001001	9	00100010	34
11110001	-15	00001010	10	00100011	35
11110010	-14	00001011	11	00100100	36
11110011	-13	00001100	12	00100101	37
11110100	-12	00001101	13	00100110	38
11110101	-11	00001110	14	00100111	39
11110110	-10	00001111	15	00101000	40
11110111	-9	00010000	16	00101001	41
11111000	-8	00010001	17	00101010	42
11111001	-7	00010010	18	00101011	43
11111010	-6	00010011	19	00101100	44
11111011	-5	00010100	20	00101101	45
11111100	-4	00010101	21	00101110	46
11111101	-3	00010110	22	00101111	47
11111110	-2	00010111	23	00110000	48
11111111	-1	00011000	24	00110001	49

TS[9:8]	T (°C)
00	+0
01	+0.25
10	+0.5
11	+0.75

Restriction

This command only actives when BUSY_N = "1".

14)R41H (TSE): Temperature Sensor Calibration Register

R41H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
TSE	W	0	0	1	0	0	0	0	0	1	41H
1 st Parameter	W	1	TSE	-	-	TO[4]	TO[3]	TO[2]	TO[1]	TO[0]	00h

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command defines as: This command indicates the driver IC temperature sensor enable and calibration function. Reserve one temperature offset TO[3:0] for calibration 1. TO[3]: mean '+' or '-', while 0 is '+'; 1 is '-' 2. TO[2:0]: mean temperature offset value <table border="1"> <thead> <tr> <th>Bit</th><th>Name</th><th>Description</th></tr> </thead> <tbody> <tr> <td>3-0</td><td>TO[3:0]</td><td> Temperature level: 0000: +0°C (default) 0001: +0.5°C 0010: +1°C 0011: +1.5°C 0100: +2°C 0101: +2.5°C 0110: +3°C 0111: +3.5°C 1000: -4°C 1001: -3.5°C 1010: -3°C 1011: -2.5°C 1100: -2°C 1101: -1.5°C 1110: -1°C 1111: -0.5°C </td></tr> <tr> <td>4</td><td>TO[4]</td><td> 0: +0.0°C (default) 1: +0.25°C </td></tr> <tr> <td>7</td><td>TSE</td><td> Internal temperature sensor enable 0: Internal temperature sensor enable.(default) 1: Internal temperature sensor disable, using external temperature sensor. </td></tr> </tbody> </table>		Bit	Name	Description	3-0	TO[3:0]	Temperature level: 0000: +0°C (default) 0001: +0.5°C 0010: +1°C 0011: +1.5°C 0100: +2°C 0101: +2.5°C 0110: +3°C 0111: +3.5°C 1000: -4°C 1001: -3.5°C 1010: -3°C 1011: -2.5°C 1100: -2°C 1101: -1.5°C 1110: -1°C 1111: -0.5°C	4	TO[4]	0: +0.0°C (default) 1: +0.25°C	7	TSE	Internal temperature sensor enable 0: Internal temperature sensor enable.(default) 1: Internal temperature sensor disable, using external temperature sensor.
Bit	Name	Description												
3-0	TO[3:0]	Temperature level: 0000: +0°C (default) 0001: +0.5°C 0010: +1°C 0011: +1.5°C 0100: +2°C 0101: +2.5°C 0110: +3°C 0111: +3.5°C 1000: -4°C 1001: -3.5°C 1010: -3°C 1011: -2.5°C 1100: -2°C 1101: -1.5°C 1110: -1°C 1111: -0.5°C												
4	TO[4]	0: +0.0°C (default) 1: +0.25°C												
7	TSE	Internal temperature sensor enable 0: Internal temperature sensor enable.(default) 1: Internal temperature sensor disable, using external temperature sensor.												
Restriction	This command only actives after R04H(PON)													

15)R42H (TSW): Temperature Sensor Write Register

R42H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
TSW	W	0	0	1	0	0	0	0	1	0	42H
1 st Parameter	W	1	WATTR[7]	WATTR[6]	WATTR[5]	WATTR[4]	WATTR[3]	WATTR[2]	WATTR[1]	WATTR[0]	00h
2 nd Parameter	W	1	WMSB[7]	WMSB[6]	WMSB[5]	WMSB[4]	WMSB[3]	WMSB[2]	WMSB[1]	WMSB[0]	00h
3 rd Parameter	W	1	WLSB[7]	WLSB[6]	WLSB[5]	WLSB[4]	WLSB[3]	WLSB[2]	WLSB[1]	WLSB[0]	00h

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command defines as:		
	This command writes the temperature.		
	1 st Parameter:		
	Bit	Name	Description
	2-0	WATTR[2:0]	Pointer setting
	5-3	WATTR[5:3]	User-defined address bits (A2, A1, A0)
	7-6	WATTR[7:6]	I2C Write Byte Number 00: 1 byte (head byte only) 01: 2 bytes (head byte + pointer) 10: 3 bytes (head byte + pointer + 1st parameter) 11: 4 bytes (head byte + pointer + 1st parameter + 2nd parameter)
	2 nd Parameter:		
	Bit	Name	Description
	7-0	WMSB[7:0]	MSByte of write-data to external temperature sensor
3 rd Parameter:	Bit	Name	Description
	7-0	WLSB[7:0]	LSByte of write-data to external temperature sensor
Restriction	This command only actives after R04H(PON)		

16)R43H (TSR): Temperature Sensor Read Register

R43H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
TSR	W	0	0	1	0	0	0	0	1	1	43H
1 st Parameter	R	1	RMSB[7]	RMSB[6]	RMSB[5]	RMSB[4]	RMSB[3]	RMSB[2]	RMSB[1]	RMSB[0]	-
2 nd Parameter	R	1	RLSB[7]	RLSB[6]	RLSB[5]	RLSB[4]	RLSB[3]	RLSB[2]	RLSB[1]	RLSB[0]	-

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command defines as: This command reads the temperature sensed by the temperature sensor. 1st Parameter: <table><tr><th>Bit</th><th>Name</th><th>Description</th></tr><tr><td>7-0</td><td>RMSB[7:0]</td><td>MSByte of read-data from external temperature sensor</td></tr></table> 2nd Parameter: <table><tr><th>Bit</th><th>Name</th><th>Description</th></tr><tr><td>7-0</td><td>RLSB[7:0]</td><td>LSByte of write-data from external temperature sensor</td></tr></table> The timing diagram illustrates the sequence of signals for the R43H (TSR) command. It includes five signals: SPI, CSB, SCL, SDA, and BUSY_N. The SPI signal shows two distinct pulses, the first labeled 'TSR command' and the second labeled 'TSR parameters'. The CSB signal is an active-low chip select that goes low during both SPI pulses. The SCL signal shows two clock bursts, one for each SPI pulse. The SDA signal shows a high pulse during the second SCL burst, labeled 'TSR value'. The BUSY_N signal is an active-low busy indicator that goes low at the start of the first SPI pulse and remains low until the end of the second SCL burst.	Bit	Name	Description	7-0	RMSB[7:0]	MSByte of read-data from external temperature sensor	Bit	Name	Description	7-0	RLSB[7:0]	LSByte of write-data from external temperature sensor
Bit	Name	Description											
7-0	RMSB[7:0]	MSByte of read-data from external temperature sensor											
Bit	Name	Description											
7-0	RLSB[7:0]	LSByte of write-data from external temperature sensor											
Restriction	This command only actives after R04H(PON)												

17)R50H (CDI): VCOM and DATA interval setting Register

R50H	Bit										
Inst/Para	RAW	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
CDI	W	0	0	1	0	1	0	0	0	0	50H
1 st Parameter	W	1	VBD[2]	VBD[1]	VBD[0]	DDX	CDI[3]	CDI[2]	CDI[1]	CDI[0]	97h

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command defines as: This command can set 2 kinds of parameters, 1.VCOM to data output interval(CDI) CDI[3:0]: This command indicates the interval of VCOM and data output. When setting the vertical back porch, the total blanking will be keep (55hsync).																						
	Bit	<table border="1"> <thead> <tr> <th>Bit</th><th>Name</th><th>Description</th></tr> </thead> <tbody> <tr> <td rowspan="17">3-0</td><td rowspan="17">CDI[3:0]</td><td>Vcom and data interval</td></tr> <tr><td>0000: 17 hsync</td></tr> <tr><td>0001: 16 hsync</td></tr> <tr><td>0010: 15 hsync</td></tr> <tr><td>0011: 14 hsync</td></tr> <tr><td>0100: 13 hsync</td></tr> <tr><td>0101: 12 hsync</td></tr> <tr><td>0110: 11 hsync</td></tr> <tr><td>0111: 10 hsync(default)</td></tr> <tr><td>1000: 9 hsync</td></tr> <tr><td>1001: 8 hsync</td></tr> <tr><td>1010: 7 hsync</td></tr> <tr><td>1011: 6 hsync</td></tr> <tr><td>1100: 5 hsync</td></tr> <tr><td>1101: 4 hsync</td></tr> <tr><td>1110: 3 hsync</td></tr> <tr><td>1111: 2 hsync</td></tr> </tbody> </table>	Bit	Name	Description	3-0	CDI[3:0]	Vcom and data interval	0000: 17 hsync	0001: 16 hsync	0010: 15 hsync	0011: 14 hsync	0100: 13 hsync	0101: 12 hsync	0110: 11 hsync	0111: 10 hsync(default)	1000: 9 hsync	1001: 8 hsync	1010: 7 hsync	1011: 6 hsync	1100: 5 hsync	1101: 4 hsync	1110: 3 hsync
Bit	Name	Description																					
3-0	CDI[3:0]	Vcom and data interval																					
		0000: 17 hsync																					
		0001: 16 hsync																					
		0010: 15 hsync																					
		0011: 14 hsync																					
		0100: 13 hsync																					
		0101: 12 hsync																					
		0110: 11 hsync																					
		0111: 10 hsync(default)																					
		1000: 9 hsync																					
		1001: 8 hsync																					
		1010: 7 hsync																					
		1011: 6 hsync																					
		1100: 5 hsync																					
		1101: 4 hsync																					
		1110: 3 hsync																					
		1111: 2 hsync																					

Internal v-sync

Internal hsync

Internal de

VCOM output location (fixed)

VCOM

Source data Output

Frame N VCOM

Frame N+1 VCOM

Frame N data

CDI setting

55 hsync-CDI setting (fixed)

VBD[2:0]: Border data selection. (from LUT output by IP port border_w[1:0])

This register will make boarder pin output being mapped to a certain gray scale.

Bit 4	Bit7-5	Description	IP setting for Border LUT select
DDX	VBD[2:0]	Gray level	
0	000	Floating	N/A
	001	Gray3	border_buf=011
	010	Gray2	border_buf=010
	011	Gray1	border_buf=001
	100	Gray0	border_buf=000
1 (default)	000	Gray0	border_buf=000
	001	Gray1	border_buf=001
	010	Gray2	border_buf=010
	011	Gray3	border_buf=011
	100	Floating	N/A

Border output voltage level: The level selection is based on mapping LUT data.

Ex: Gray 1 waveform is mapping to 15V, without VCOM offset, the real output on Boarder pin shall be 15V.

Boarder output will follow FOPT definition being defined in R00h.

Restriction

18) R51H (LPD): Lower Power Detection Register

R51H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
LPD	W	0	0	1	0	1	0	0	0	1	51H
1 st Parameter	R	1	-	-	-	-	-	-	-	LPD	-

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command defines as: This command indicates the input power condition. Host can read this data to understand the battery's condition. When LPD="1", system input power is normal. When LPD="0", system input power is lower ($VDD < 2.5V$, which could be select in RE4H (LVSEL)). 1st Parameter: <table border="1"> <tr> <td>Bit 0</td><td>LPD</td></tr> <tr> <td>0</td><td>Low power input.</td></tr> <tr> <td>1</td><td>Normal status.</td></tr> </table>	Bit 0	LPD	0	Low power input.	1	Normal status.
Bit 0	LPD						
0	Low power input.						
1	Normal status.						
Restriction	This command only actives when BUSY_N = "1".						

19)R61H (TRES): Resolution setting

R61H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
TRES	W	0	0	1	1	0	0	0	0	1	61H
1 st Parameter	W	1	-	-	-	-	-	-	HRES(9)	HRES(8)	00h
2 nd Parameter	W	1	HRES(7)	HRES(6)	HRES(5)	HRES(4)	HRES(3)	HRES(2)	0	0	00h
3 rd Parameter	W	1	-	-	-	-	-	-	VRES(9)	VRES(8)	00h
4 th Parameter	W	1	VRES(7)	VRES(6)	VRES(5)	VRES(4)	VRES(3)	VRES(2)	VRES(1)	VRES(0)	00h

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command define as follows: When using register: Horizontal display resolution(source) = HRES Vertical display resolution(gate) = VRES Note: No matter HRES[9:8],HRES[1:0],VRST[9] value being filled, it's always be 00b. Channel disable calculation: GD : First G active = G0; LAST active GD= first active +VRES[9:0] -1 SD : First active channel: =S0 ; LAST active SD= first active +HRES[9:2]*4-1 EX :176X296 GD: First G active = G0 LAST active GD= 0+296-1= 295; (G295) SD : First active channel: =S0 LAST active SD=0+44*4-1=175; (S175) Note : Only supports source 176.ch for source 160ch. above
Restriction	Horizontal resolution should be 4-multiple.

20) R65H(GSST): Gate/Source Start Setting Register

R65H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
GSST	W	0	0	1	1	0	0	1	0	1	65H
1 st Parameter	W	1	-	-	-	-	-	-	S_start[9]	S_start[8]	00h
2 nd Parameter	W	1	S_start[7]	S_start[6]	S_start[5]	S_start[4]	S_start[3]	S_start[2]	0	0	00h
3 rd Parameter	W	1	-	-	-	-	-	-	G_start[9]	G_start[8]	00h
4 th Parameter	W	1	G_start[7]	G_start[6]	G_start[6]	G_start[4]	G_start[3]	G_start[2]	G_start[1]	G_start[0]	00h

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command define as follows: Note: No matter S_start[9:8], S_start [1:0], VRST[9] value being filled, it's always be 00b. 1.S_Start [7:0] describe which source output line is the first date line 2.G_Start[8:0] describe which gate line is the first scan line
Restriction	S_Start should be the multiple of 4

21)R70H (REV): REVISION register

R70H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
REV	W	0	0	1	1	1	0	0	0	0	70H
1 st Parameter	R	1	0	0	0	0	0	0	1	1	03h
2 nd Parameter	R	1	0	0	0	0	0	0	1	0	02h
3 rd Parameter	R	1	0	0	0	0	0	0	0	1	01h

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command defines as: 1st & 2nd & 3rd Parameter: <table border="1"> <tr> <th>Bit</th><th>Description</th></tr> <tr> <td>7-0</td><td>CHIP_REV</td></tr> </table>	Bit	Description	7-0	CHIP_REV
Bit	Description				
7-0	CHIP_REV				
Restriction					

24)R82H (VDCS): VCOM DC Setting Register

R82H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
VDCS	W	0	1	0	0	0	0	0	1	0	82H
1 st Parameter	W	1	MTP_VC M	VDCS[6]	VDCS[5]	VDCS[4]	VDCS[3]	VDCS[2]	VDCS[1]	VDCS[0]	00h

NOTE: "-" Don't care, can be set to VDD or GND level

Description

-The command defines as:

This command set the VCOM DC value. Driver will base on this value for VCM_DC.

1st Parameter:

Bit	Name	Description
6-0	VDCS[6:0]	VCOM value
		VCOM[6:0] Voltage(V) VCOM[5:0] Voltage(V) VCOM[6:0] Voltage(V)
		0000000 00h 0(default) 00111100 1Ch -1.4 0111000 38h -2.8
		0000001 01h -0.05 00111101 1Dh -1.45 0111001 39h -2.85
		0000010 02h -0.1 00111110 1Eh -1.5 0111010 3Ah -2.9
		0000011 03h -0.15 00111111 1Fh -1.55 0111011 3Bh -2.95
		0000100 04h -0.2 0100000 20h -1.6 0111100 3Ch -3
		0000101 05h -0.25 0100001 21h -1.65 0111101 3Dh -3.05
		0000110 06h -0.3 0100010 22h -1.7 0111110 3Eh -3.1
		0000111 07h -0.35 0100011 23h -1.75 0111111 3Fh -3.15
		0001000 08h -0.4 0100100 24h -1.8 1000000 40h -3.2
		0001001 09h -0.45 0100101 25h -1.85 1000001 41h -3.25
		0001010 0Ah -0.5 0100110 26h -1.9 1000010 42h -3.3
		0001011 0Bh -0.55 0100111 27h -1.95 1000011 43h -3.35
		0001100 0Ch -0.6 0101000 28h -2 1000100 44h -3.4
		0001101 0Dh -0.65 0101001 29h -2.05 1000101 45h -3.45
		0001110 0Eh -0.7 0101010 2Ah -2.1 1000110 46h -3.5
		0001111 0Fh -0.75 0101011 2Bh -2.15 1000111 47h -3.55
		0010000 10h -0.8 0101100 2Ch -2.2 1001000 48h -3.6
		0010001 11h -0.85 0101101 2Dh -2.25 1001001 49h -3.65
		0010010 12h -0.9 0101110 2Eh -2.3 1001010 4Ah -3.7
		0010011 13h -0.95 0101111 2Fh -2.35 1001011 4Bh -3.75
		0010100 14h -1 0110000 30h -2.4 1001100 4Ch -3.8
		0010101 15h -1.05 0110001 31h -2.45 1001101 4Dh -3.85
		0010110 16h -1.1 0110010 32h -2.5 1001110 4Eh -3.9
		0010111 17h -1.15 0110011 33h -2.55 1001111 4Fh -3.95
		0011000 18h -1.2 0110100 34h -2.6 1010000 50h -4
		0011001 19h -1.25 0110101 35h -2.65 other -4
		0011010 1Ah -1.3 0110110 36h -2.7
		0011011 1Bh -1.35 0110111 37h -2.75

	7	MTP_VCM	Follow MTP VCOM value in MTP mode 0: From the setting of MTP (default) 1: From the setting of register
Restriction			

25) R83H (PTL): Partial Window Register

R83H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
PTL	W	0	1	0	0	0	0	0	1	1	83H
1 st Parameter	W	1	-	-	-	-	-	-	HRST[9]	HRST[8]	00h
2 nd Parameter	W	1	HRST[7]	HRST[6]	HRST[5]	HRST[4]	HRST[3]	HRST[2]	-	-	00h
3 rd Parameter	W	1	-	-	-	-	-	-	HRED[9]	HRED[8]	00h
4 th Parameter	W	1	HRED[7]	HRED[6]	HRED[5]	HRED[4]	HRED[3]	HRED[2]	-	-	00h
5 th Parameter	W	1	-	-	-	-	-	-	VRST[9]	VRST[8]	00h
6 th Parameter	W	1	VRST[7]	VRST[6]	VRST[5]	VRST[4]	VRST[3]	VRST[2]	VRST[1]	VRST[0]	00h
7 th Parameter	W	1	-	-	-	-	-	-	VRED[9]	VRED[8]	00h
8 th Parameter	W	1	VRED[7]	VRED[6]	VRED[5]	VRED[4]	VRED[3]	VRED[2]	VRED[1]	VRED[0]	00h
9 th Parameter	W	1	-	-	-	-	-	-	-	PMODE	00h

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-This command sets partial window. <table border="1"> <thead> <tr> <th>Name</th><th>Description</th></tr> </thead> <tbody> <tr> <td>HRST[9:2]</td><td>Horizontal start address</td></tr> <tr> <td>HRED[9:2]</td><td>Horizontal end address. HRED must be greater than HRST.</td></tr> <tr> <td>VRST[9:0]</td><td>Vertical start address.</td></tr> <tr> <td>VRED[9:0]</td><td>Vertical end address. VRED must be greater than VRST.</td></tr> <tr> <td>PMODE</td><td>0: disable partial mode(default) 1: enable partial mode</td></tr> </tbody> </table> Note: No matter HRST[1:0], HRST[9:8], HRED[9:8], VRST[9], VRED[9] value being filled, it's always be 00b. No matter HRED[1:0] value being filled, it's always be 11b. Gates scan both inside and outside of the partial window.	Name	Description	HRST[9:2]	Horizontal start address	HRED[9:2]	Horizontal end address. HRED must be greater than HRST.	VRST[9:0]	Vertical start address.	VRED[9:0]	Vertical end address. VRED must be greater than VRST.	PMODE	0: disable partial mode(default) 1: enable partial mode
Name	Description												
HRST[9:2]	Horizontal start address												
HRED[9:2]	Horizontal end address. HRED must be greater than HRST.												
VRST[9:0]	Vertical start address.												
VRED[9:0]	Vertical end address. VRED must be greater than VRST.												
PMODE	0: disable partial mode(default) 1: enable partial mode												
Restriction													

26) R90H (PGM): Program Mode

R90H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
PGM	W	0	1	0	0	1	0	0	0	0	90H

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command define as follows: After this command is issued, the chip would enter the program mode. The mode would return to standby by hardware reset.
Restriction	

27) R91H (APG): Active Program

R91H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
APG	W	0	1	0	0	1	0	0	0	1	91H

NOTE: "-" Don't care, can be set to VDD or GND level

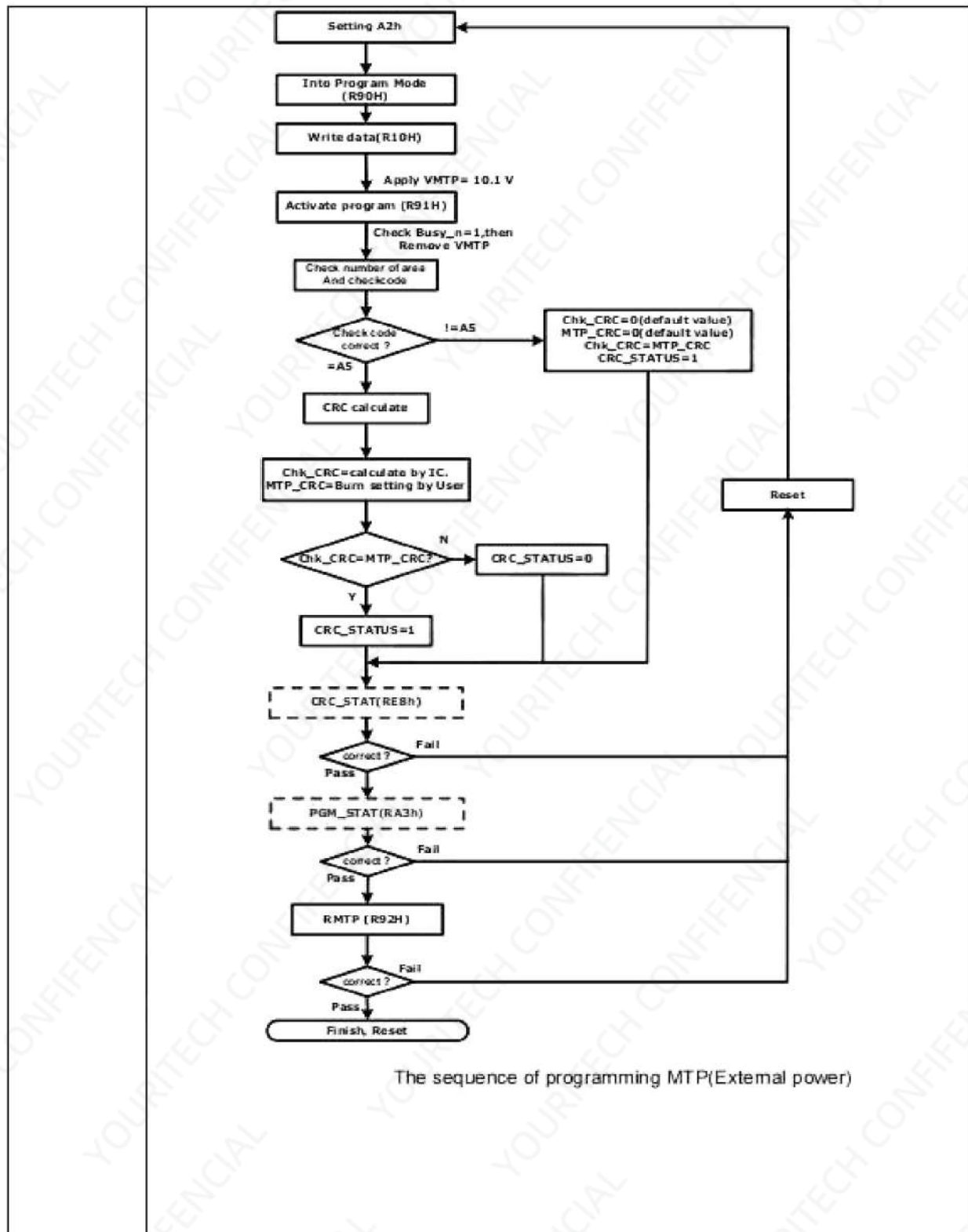
Description	-The command define as follows: After this command is transmitted, the programming state machine would be activated.
Restriction	The BUSY flag would change state from 0 to 1 while the programming is completed.

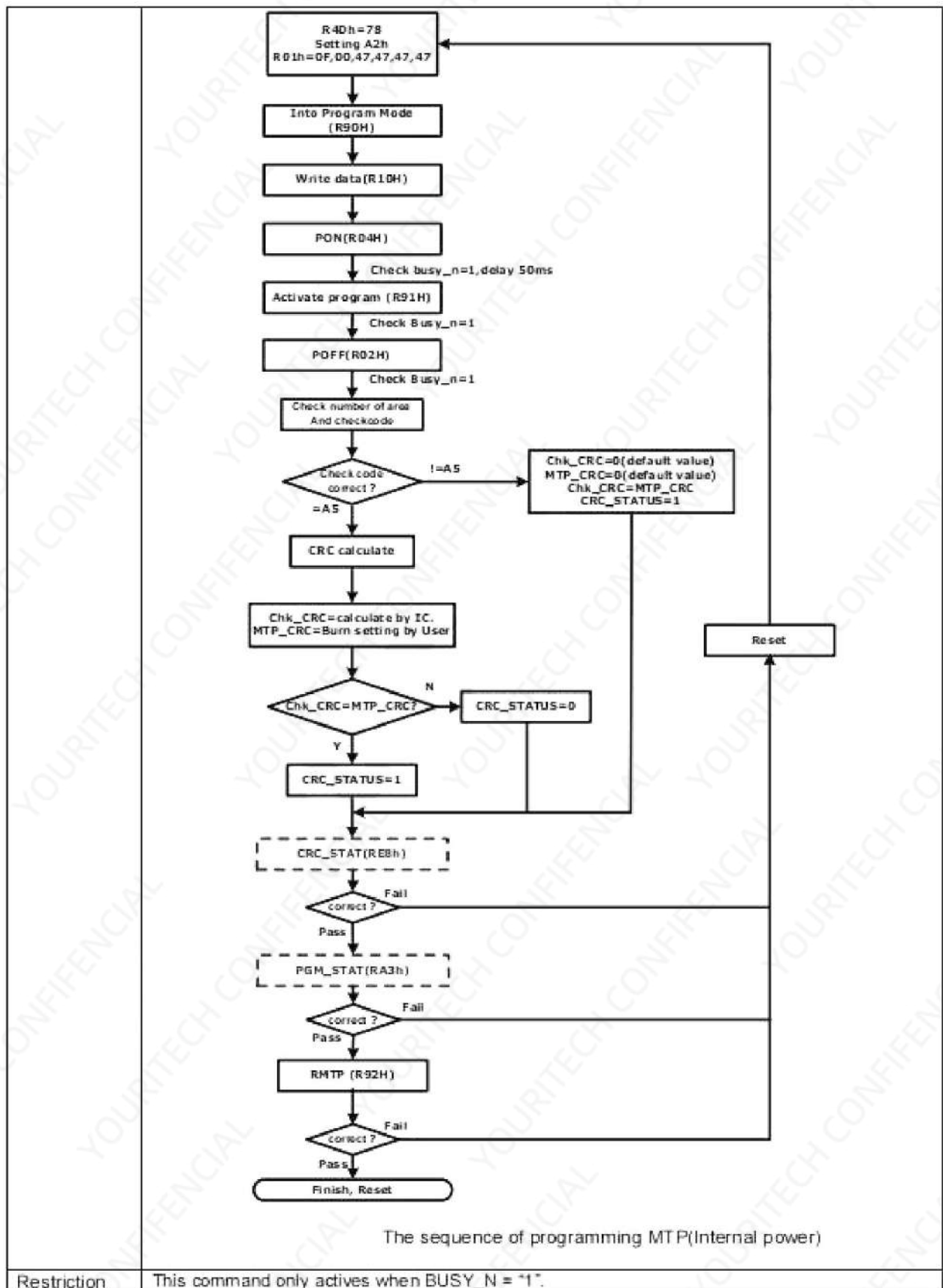
28) R92H (RMTP): Read MTP Data

R92H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
RMTP	W	0	1	0	0	1	0	0	1	0	92H
1 st Parameter	R	1	Dummy								-
2 nd Parameter	R	1	The data of address 0x000 in the MTP								-
3 rd Parameter	R	1	The data of address 0x001 in the MTP								-
4 th Parameter	R	1	:								-
5 th Parameter	R	1	The data of address (n-1) in the MTP								-
6 th ~(m-1) th Parameter	R	1									-
m th Parameter	R	1	The data of address (n) in the MTP								-

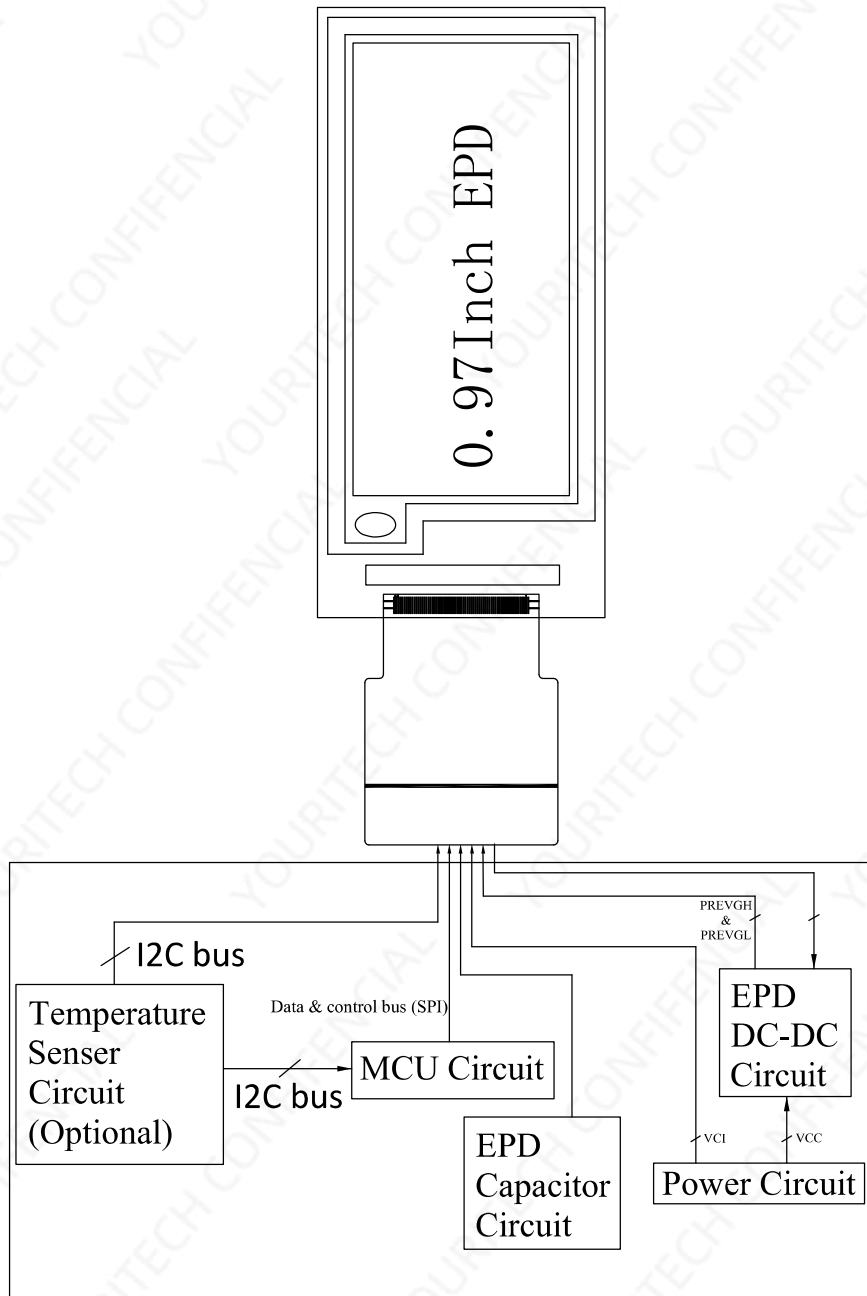
NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command define as follows: The command is used for reading the content of MTP for checking the data of programming. The value of (n) is depending on the amount of programmed data, the max address = 0x17FF
-------------	---

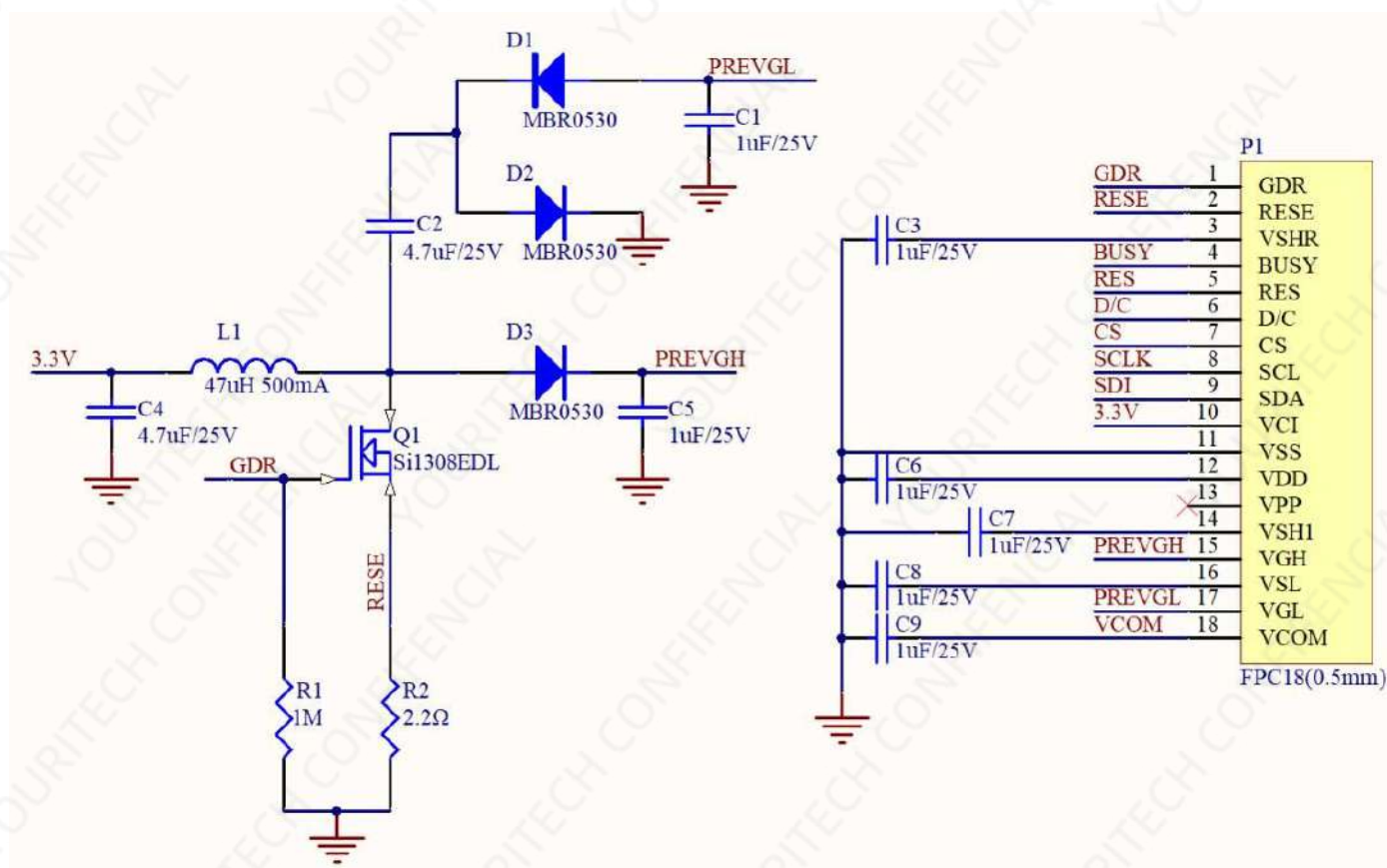




8. Block Diagram



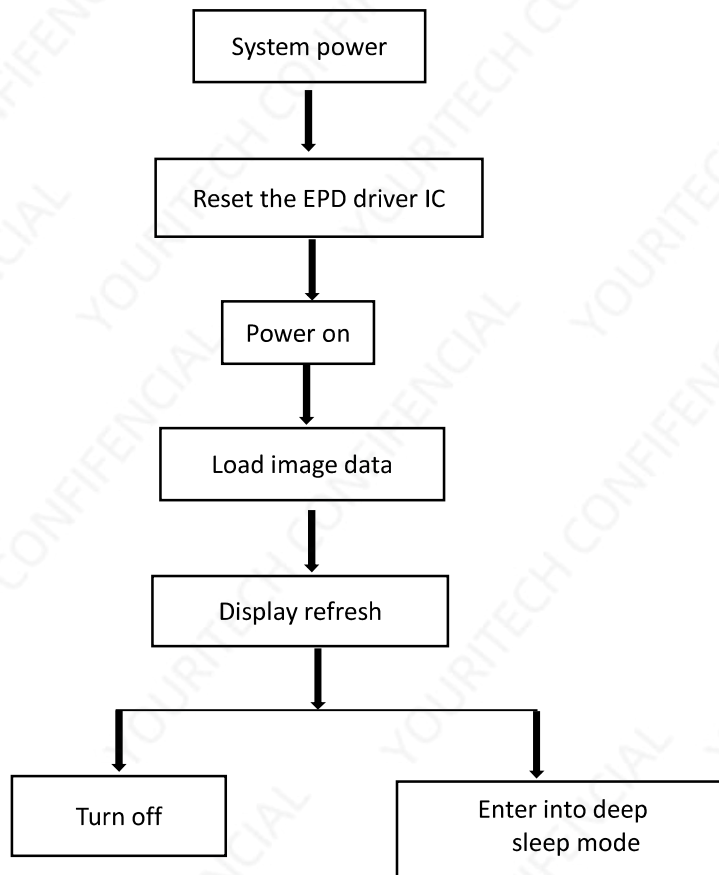
9. Typical Application Circuit with SPI Interface



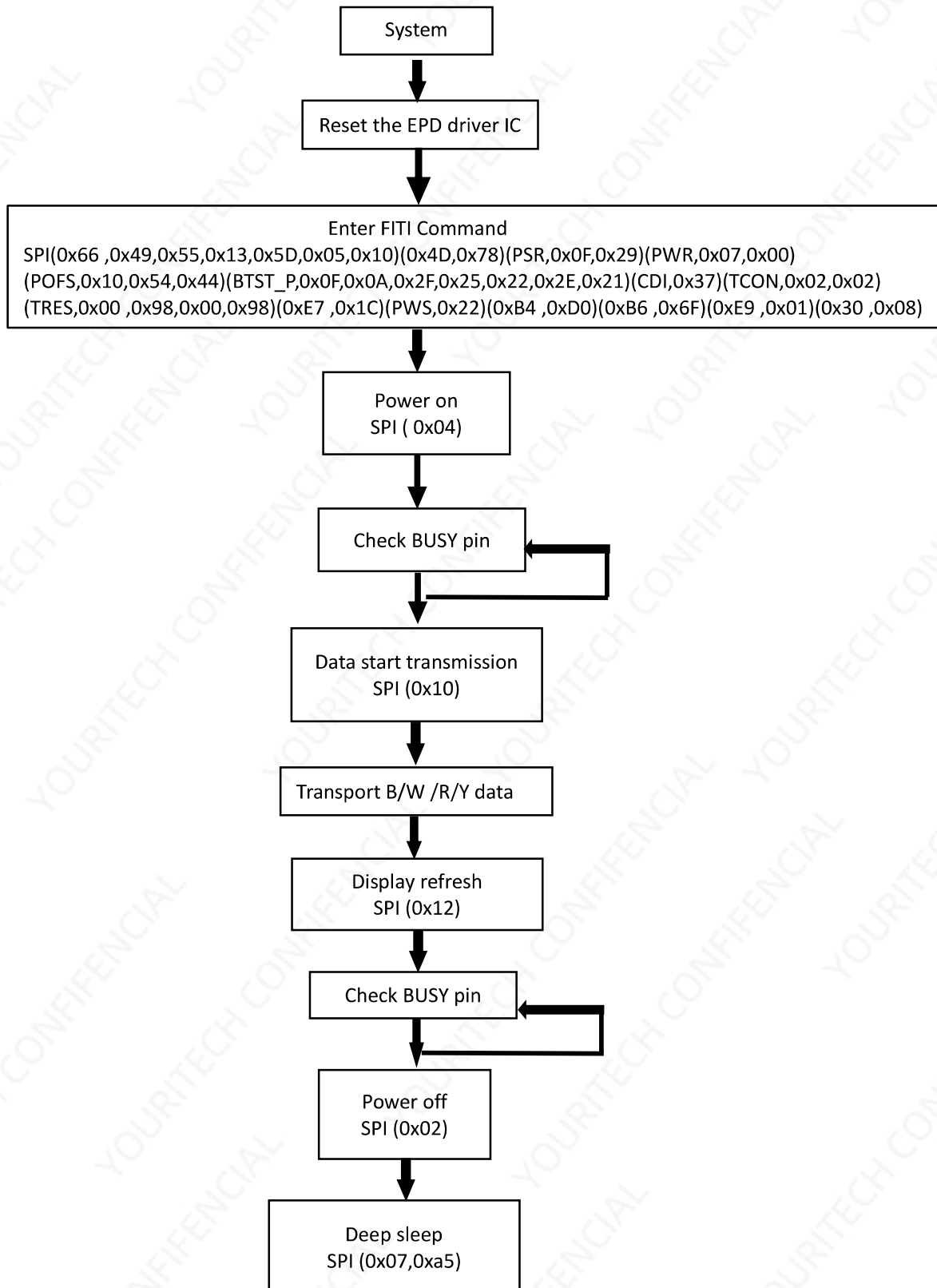
Part Name	Requirements for spare part
C1—C9	0603/0805; X5R/X7R; Voltage Rating: $\geq 25V$
R1、R2	0603/0805; 1% variation, $\geq 0.05W$
D1—D3	MBR0530: 1) Reverse DC Voltage $\geq 30V$ 2) $I_o \geq 500mA$ 3) Forward voltage $\leq 430mV$
Q1	Si1308EDL: 1) Drain-Source breakdown voltage $\geq 30V$ 2) $V_{gs(th)}$ $\leq 1.5V$ 3) $R_{ds(on)} \leq 400m\Omega$
L1	NR3015: $I_o = 500mA (max)$
P1	18pins, 0.5mm pitch

10. Typical Operating Sequence

10.1 LUT from OTP Operation Flow



10.2 OTP Operation Reference Program Code



11. Reliability Test

NO	Test items	Test condition
1	Low-Temperature Storage	T = -25°C, 500 h Test in white pattern
2	High-Temperature Storage	T=60°C, RH=35%, 500h Test in white pattern
3	High-Temperature Operation	T=40°C, RH=30%, 500h
4	Low-Temperature Operation	0°C, 500h
5	High-Temperature, High-Humidity Operation	T=40°C, RH=90%, 500h
6	High- Temperature, High -Humidity Storage	T=60°C, RH=80%, 500h Test in white pattern
7	Temperature Cycle	1 cycle:[-25°C 30min]→[+60 °C 30 min] : 100 cycles Test in white pattern

Note: 1. Stay white pattern for storage and non-operation test.

2. Operation is black→white→red→yellow pattern, the interval is 150s.

3. Put in 20°C--25°C for 1hour after test finished, The function ,appearance and display performance is OK.

12. Quality Assurance

12.1 Environment

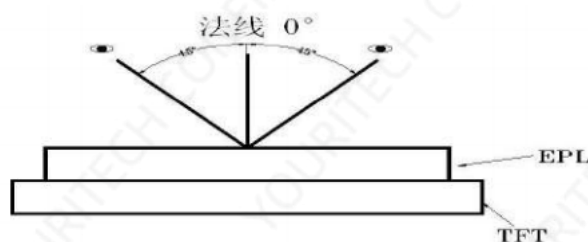
Temperature: $23 \pm 2^{\circ}\text{C}$

Humidity: $55 \pm 10\%\text{RH}$

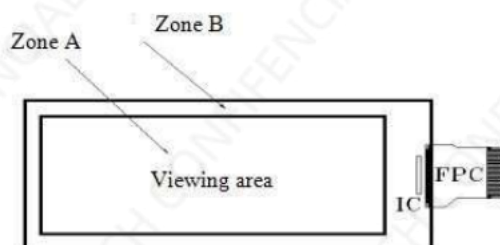
12.2 Illuminance

Brightness: 1200~1500LUX; distance: 20-30CM; Angle: Relate 45° surround.

12.3 Inspect method



12.4 Display are



12.5 Ghosting test method

Three-color ghosting is measured with following transition from horizontal 4 scale pattern to vertical 4 scale pattern. The listed optical characteristics are only guaranteed under the controller & waveform provided by YOURITECH.



1) Measurement Instruments: X-rite i1Pro

2) Ghosting formula:

W ghosting: $\Delta E = \text{Max} (\Delta E_{ab}(Y-W, R-W), \Delta E_{ab}(Y-W, W-W), \Delta E_{ab}(Y-W, B-W), \Delta E_{ab}(R-W, W-W), \Delta E_{ab}(R-W, B-W), \Delta E_{ab}(W-W, B-W))$

K ghosting: $\Delta E = \text{Max} (\Delta E_{ab}(Y-B, R-B), \Delta E_{ab}(Y-B, W-B), \Delta E_{ab}(Y-B, B-B), \Delta E_{ab}(R-B, W-B), \Delta E_{ab}(R-B, B-B), \Delta E_{ab}(W-B, B-B))$

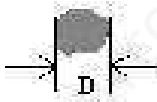
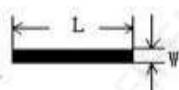
R ghosting: $\Delta E = \text{Max} (\Delta E_{ab}(Y-R, R-R), \Delta E_{ab}(Y-R, W-R), \Delta E_{ab}(Y-R, B-R), \Delta E_{ab}(R-R, W-R), \Delta E_{ab}(R-R, B-R), \Delta E_{ab}(W-R, B-R))$

Y ghosting: $\Delta E = \text{Max} (\Delta E_{ab}(Y-Y, R-Y), \Delta E_{ab}(Y-Y, W-Y), \Delta E_{ab}(Y-Y, B-Y), \Delta E_{ab}(R-Y, W-Y), \Delta E_{ab}(R-Y, B-Y), \Delta E_{ab}(W-Y, B-Y))$

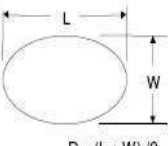
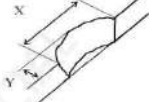
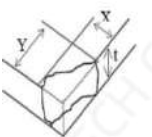
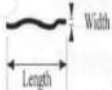
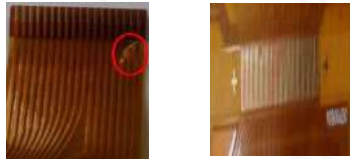


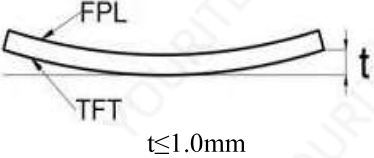
12.6 Inspection standard

12.6.1 Electric inspection standard

NO.	Item	Standard	Defect level	Method	Scope
1	Display	Clear display Display complete Display uniform	MA	Visual inspection	Zone A
2	Black/White spots	 $D \leq 0.25\text{mm}$, Allowed $0.25\text{mm} < D \leq 0.4\text{mm}$ 。 $N \leq 4$ allowable $D > 0.4\text{mm}$ is not allowed	MI		
3	Black/White lines (No switch)	 $L \leq 0.4\text{mm}, W \leq 0.1\text{mm}$ negligible $0.4\text{mm} < L \leq 1.0\text{mm}$ $0.1\text{mm} < W \leq 0.4\text{mm}$ $N \leq 4$ allowable $L > 1.0\text{mm} , W > 0.4\text{mm}$ is not allowed			
4	Ghost image	Allowed in switching process	MI	Visual inspection	
5	Flash dot / Multilateral	Flash points are allowed when switching screens Multilateral colors outside the frame are allowed for fixed screen time	MI	Visual/ Inspection card	Zone A Zone B
6	Segmented display	Selection segments are all displayed, and other segments are not displayed after the selection segment.	MA	Visual inspection	Zone A
7	Short circuit/ Circuit break/ Abnormal Display	Not Allow			

12.6.2 Appearance inspection standard

NO.	Item	Standard	Defect level	Method	Scope
1	B/W spots /Bubble/ Foreign bodies/ Dents	 $D = (L + W) / 2$ $D \leq 0.25\text{mm}$ negligible $0.25\text{mm} < D \leq 0.4\text{mm}$ $N \leq 4$ allowable $D > 0.4\text{mm}$ is not allowed	MI	Visual inspection	Zone A
2	Glass crack	Not Allow	MA	Visual / Microscope	Zone A Zone B
3	\Dirty	Allowed if can be removed	MI		Zone A Zone B
4	Chips/Scratch/ Edge crown	 $X \leq 3\text{mm}$, $Y \leq 0.5\text{mm}$ And without affecting the electrode is permissible  $2\text{mm} \leq X$ or $2\text{mm} \leq Y$ $t =$ not counted, and without affecting the electrode, permissible  $W \leq 0.1\text{mm}$, $L \leq 5\text{mm}$, without affecting the electrode, $n \leq 2$	MI	Visual / Microscope	Zone A Zone B
5	TFT Cracks	 Not Allow	MA	Visual / Microscope	Zone A Zone B
6	Dirty/ foreign body	Allowed if can be removed/ allow	MI	Visual / Microscope	Zone A / Zone B
7	FPC broken/ FPC oxidation / scratch	 Not Allow	MA	Visual / Microscope	Zone B

8	B/W Line	 $L \leq 0.4\text{mm}, W \leq 0.1\text{mm}$ negligible $0.4\text{mm} < L \leq 1.0\text{mm}$ $0.1\text{mm} < W \leq 0.4\text{mm}$ $N \leq 4$ allowable $L > 1.0\text{mm}, W > 0.4\text{mm}$ is not allowed	MI	Visual / Ruler	Zone B
9	TFT edge bulge /TFT chromatic aberration	TFT edge bulge: $X \leq 3\text{mm}, Y \leq 0.3\text{mm}$ Allowed TFT chromatic aberration :Allowed	MI	Visual / Microscope	Zone A Zone B
10	Electrostatic point	$D \leq 0.2\text{mm}$, allow $0.2\text{mm} < D \leq 0.35\text{mm}$, $n \leq 4$ allow $D > 0.35\text{mm}$ is not allowed ($n \leq 5$ items are allowed within 5 mm in diameter)	MI	Visual / Microscope	Zone A
11	PCB damaged/ Poor welding/ Curl	PCB (Circuit area) damaged Not Allow PCB Poor welding Not Allow PCB Curl $\leq 1\%$	MI	Visual / Ruler	Zone B
12	Edge glue height/ Edge glue bubble	Edge Adhesives $H \leq \text{PS surface}$ (Including protect film) Edge adhesives seep in $\leq 1/2$ Margin width Length excluding Edge adhesives bubble: bubble Width $\leq 1/2$ Margin width; Length $\leq 5.0\text{mm}$. $n \leq 5$	MI		
13	Protect film	Surface scratch but not effect protect function, Allow	MI	Visual Inspection	
14	Silicon glue	Thickness $\leq \text{PS surface (With protect film)}$: Full cover the IC; Shape: The width on the FPC $\leq 0.5\text{mm}$ (Front) The width on the FPC $\leq 1.0\text{mm}$ (Back) smooth surface, No obvious raised.	MI	Visual Inspection	
15	Warp degree (TFT substrate)	 $t \leq 1.0\text{mm}$	MI	Ruler	
16	Color difference in COM area (Silver point area)	Allowed		Visual Inspection	

13. Matched Development Kit

Our Development Kit designed for SPI E-paper Display aims to help users to learn how to use E-paper Display more easily. It can refresh black-white E-paper Display, three-color (black, white and red/Yellow) E-paper Display and four-color (black, white, red and yellow) YOURITECH's E-paper Display. And it is also added the functions of USB serial port, FLASH chip, font chip, current detection ect.

Development Kit consists of the development board and the pinboard. Supported development platforms include STM32, ESP32, ESP8266, Arduino UNO, etc.

14. Handling, Safety and Environmental Requirements

WARNING
The display glass may break when it is dropped or bumped on a hard surface. Handle with care. Should the display break, do not touch the electrophoretic material. In case of contact with electrophoretic material, wash with water and soap.

CAUTION
The display module should not be exposed to harmful gases, such as acid and alkali gases, which corrode electronic components.
Disassembling the display module can cause permanent damage and invalidate the warranty agreements.

Observe general precautions that are common to handling delicate electronic components. The glass can break and front surfaces can easily be damaged. Moreover the display is sensitive to static electricity and other rough environmental conditions.

Data sheet status	
Product specification	The data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

Product Environmental certification
RoHS

15. Precautions

- (1) Do not apply pressure to the EPD panel in order to prevent damaging it.
- (2) Do not connect or disconnect the interface connector while the EPD panel is in operation.
- (3) Do not touch IC bonding area. It may scratch TFT lead or damage IC function.
- (4) Please be mindful of moisture to avoid its penetration into the EPD panel, which may cause damage during operation.
- (5) If the EPD Panel / Module is not refreshed every 24 hours, a phenomena known as “Ghosting” or “Image Sticking” may occur. It is recommended to refresh the ESL/ EPD Tag every 24 hours in use case. It is recommended that customer ships or stores the ESL / EPD Tag with a completely white image to avoid this issue.
- (6) High temperature, high humidity, sunlight or fluorescent light may degrade the EPD panel's performance. Please do not expose the unprotected EPD panel to high temperature, high humidity, sunlight, or fluorescent for long periods of time.